

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

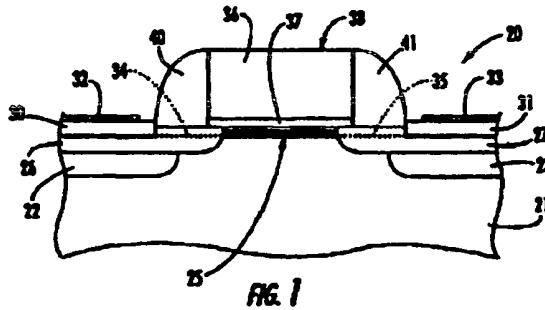
PATENT NO. : 6,891,188 B2  
APPLICATION NO. : 10/717374  
DATED : May 15, 2005  
INVENTOR(S) : Mears et al.

Page 1 of 2

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In the Drawings

Delete: FIG. 1  
Insert: New FIG. 1



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It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 9, Lines 44-46 Delete: "In other processes and devices the structures of the present invention may be formed on a portion of a wafer or across substantially all of a wafer."

Column 9, Line 59      Delete: "also formed"  
                            Insert: --also be formed--

Signed and Sealed this

Twenty-sixth Day of September, 2006



JON W. DUDAS  
*Director of the United States Patent and Trademark Office*